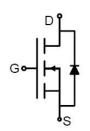


Feature

• 30V,20A

$$\begin{split} &R_{\text{DS (ON)}} \leqslant 13 \text{m } \Omega \text{ @V}_{\text{GS}} = 10 \text{V} & \text{TYP:9 m } \Omega \\ &R_{\text{DS (ON)}} \leqslant 16 \text{m } \Omega \text{ @V}_{\text{GS}} = 4.5 \text{V} & \text{TYP:13 m } \Omega \end{split}$$

- Advanced Trench Technology
- Lead free product is acquired
- Excellent R DS (ON) and Low Gate Charge



Schematic Diagram

Application

- PWM applications
- Load Switch
- Power management



Marking and pin Assignment

Package Marking and Ordering Information

Device Marking	evice Marking Device		Reel Size	Tape width	Quantity (PCS)	
0903Q	AP0903Q	PDFN3X3-8L	13 inch	-	5000	

ABSOLUTE MAXIMUM RATINGS (T_a=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _G s	±20	V
Continuous Drain Current (T _C =25℃)	ID	20	Α
Continuous Drain Current (T _C =100℃)	I _D	14	Α
Pulsed Drain Current (1)	I _{DM}	75	Α
Single Pulsed Avalanche Energy (2)	Eas	65	mJ
Power Dissipation	P _D	9.8	W
Thermal Resistance from Junction to Case ⁽⁴⁾	Rejc	12.8	°C/W
Junction Temperature	TJ	150	°C
Storage Temperature	T _{STG}	-55~ +150	°C



MOSFET ELECTRICAL CHARACTERISTICS(T_a=25℃ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Туре	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	30	-	-	V
Zero gate voltage drain current	IDSS	V _{DS} =30V, V _{GS} = 0V	-	-	1	μA
Gate-body leakage current	Igss	V _{GS} =±20V,V _{DS} = 0V	-	-	±100	nA
Gate threshold voltage ⁽³⁾	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.4	2.5	V
	Б	V _{GS} =10V, I _D =20A	-	9	13	mΩ
Drain-source on-resistance ⁽³⁾	R _{DS(on)}	V _{GS} =4.5V, I _D =10A	-	13	16	
Dynamic characteristics						
Input Capacitance	Ciss	V _{DS} =15V, V _{GS} =0V, f =1MHz	-	1011	-	pF
Output Capacitance	Coss		-	142	-	
Reverse Transfer Capacitance	Crss		-	119	-	
Switching characteristics						
Turn-on delay time	t _{d(on)}	V_{DD} =15V, I_D =20A, R_L =6 Ω V_{GS} =10V, R_G =1 Ω	-	6	-	ns
Turn-on rise time	tr		-	5	-	
Turn-off delay time	t _{d(off)}		-	25	-	
Turn-off fall time	tf		-	7	-	
Total Gate Charge	Qg		-	19	-	nC
Gate-Source Charge	Qgs	VDS=15V, ID=10A,	-	6.3	-	
Gate-Drain Charge	Qgd	- VGS=10V	-	4.5	-	
Source-Drain Diode characteristics	·	•	·	•		
Diode Forward voltage ⁽³⁾	V _{DS}	V _{GS} =0V, I _S =10A	-	-	1.2	V
Diode Forward current ⁽⁴⁾	Is		-	-	20	Α

Notes:

- 1. Repetitive Rating: pulse width limited by maximum junction temperature
- 2. EAS Condition: T_J =25 $^{\circ}$ C, V_{DD} =15V, R_G =25 $^{\circ}$ C,L=0.5mH
- 3. Pulse Test: pulse width≤300µs, duty cycle≤2%
- 4. Surface Mounted on FR4 Board,t≤10 sec



Typical Performance Characteristics

Figure1: Output Characteristics

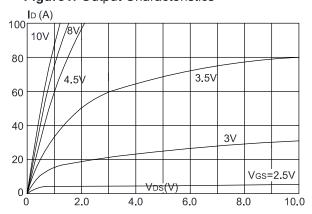


Figure 3:On-resistance vs. Drain Current

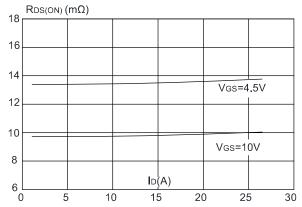


Figure 5: Gate Charge Characteristics

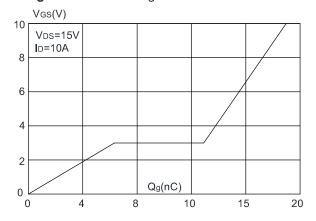


Figure 2: Typical Transfer Characteristics

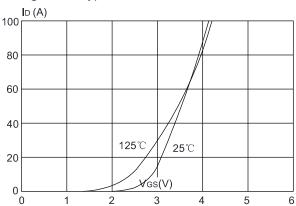


Figure 4: Body Diode Characteristics

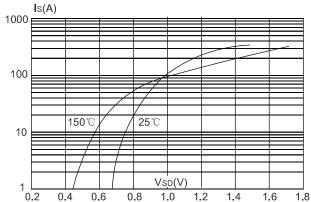
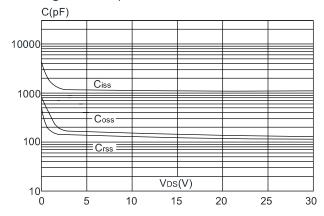


Figure 6: Capacitance Characteristics





DATA SHEET

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

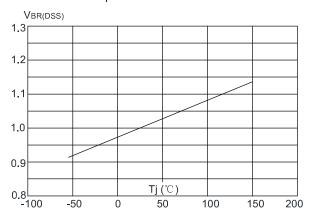


Figure 9: Maximum Safe Operating Area

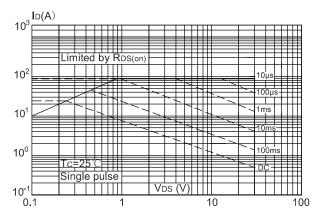


Figure.11: Maximum Effective
Transient Thermal Impedance, Junction-to-Case

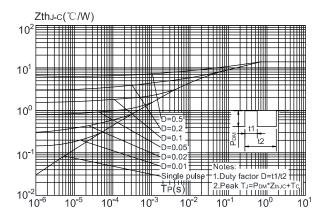


Figure 8: Normalized on Resistance vs. Junction Temperature

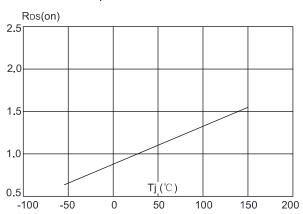
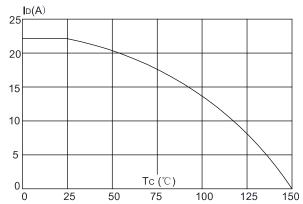


Figure 10: Maximum Continuous Drain Current vs. Case Temperature





Test Circuit

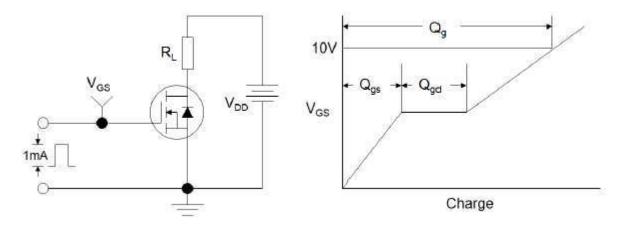


Figure1:Gate Charge Test Circuit & Waveform

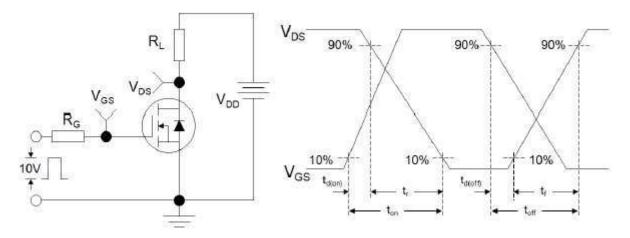


Figure 2: Resistive Switching Test Circuit & Waveforms

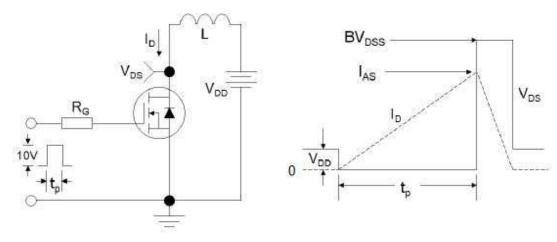


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms



PDFN3X3-8L Package Information

